

RFA570 eXpress cure Adhesive Film

Description and Features

This unique product has principally been designed for use with RP570 and RP570 FR eXpress cure epoxy prepregs, as a core-bond adhesive. The unique characteristics of this product enable it to be cured in a press in 4 minutes at 140°C, thereby speeding up the processing of honeycomb sandwich panels. Can be used with both nomex and aluminium honeycombs. The product will also cure in autoclave, with typical curing cycle of 4 minutes once the mould tool has stabilised at 140°C. Fully compatible with PRF's full range of epoxy prepreg systems.

- › Available in 150g/m² and 300g/m² standard weights
- › Available supported/unsupported
- › Supplied on roll form
- › Available from stock

Cure cycle:

140°C 4 minutes

Gel time:

@140°C 65-85s

Tg:

DMA

E' Onset: 105°C

Tanδ Peak: 150°C

Outlife:

Currently in testing: 20 days at 20°C

Flatwise Tensile Test of Honeycomb sandwich panel:

Film Wt Mode	Core Material	Cell size	Thickness	Failure
150gsm	Nomex	3mm	8mm	Core Failure
300gsm	Aluminium	3mm	8mm	Core Failure

Lap Shear Strength

38 MPa

All values are nominal.

Important notice

All statements, technical information and recommendations offered are only for consideration and evaluation. Whilst they are believed to be accurate they are not guaranteed and are provided without warranty of any kind. No undertaking is given that the goods/products supplied are fit for any particular purpose and the buyer/user should rely upon its own tests to establish suitability of the goods/products for its particular purpose. The buyer/user shall assume all risks and liabilities in connection therewith.

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